Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	**: Required Field*	

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-10-28
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32WB06CCF7TR	T3E0*F1618B9	A	996S	2024-10-28
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	10	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
1	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Tin/Silver/Copper (SAC405)	Not Applicable	NAC	0	
Package designator	Package size	Number of instances	Shape	
WLCSP	NA	23	Bulk solder	
Comment	Package : 01C1 WLCSP MSL1 8165249			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false

Exemption Id.	**Description**
,	

QueryList : REACH-27th June 2024				**Response**
QUERY				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**T3E0*F1618B9**		10.2515		9000000.0	1000000.0
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	7.847	mg	supplier	die	Silicon (Si)	7440-21-3		7.440	mg	948119	725709
				supplier	metallization	Aluminium (Al)	7429-90-5		0.020	mg	2496	1910
				supplier	metallization	Copper (Cu)	7440-50-8		0.172	mg	21929	16785
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.056	mg	7131	5458
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	357	273
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	178	136
				supplier	Passivation	Silicon Nitride	12033-89-5		0.043	mg	5527	4230
				supplier	Passivation	Silicon Oxide	7631-86-9		0.112	mg	14263	10917
Plating Seed layer 1	Other inorganic materials	0.004	mg	supplier	Alloy	Ti	7440-32-6		0.001	mg	200963	71
				supplier	Alloy	Cu	7440-50-8		0.003	mg	799037	281
UBM	Other inorganic materials	0.130	mg	supplier	Alloy	Cu	7440-50-8		0.130	mg	1000000	12632
Re-passivatipon layer (HD8820)	Other organic materials	0.083	mg	supplier	Polymer	Proprietary polymer	Proprietary		0.074	mg	900000	7252
				supplier	Polymer	Additives	Proprietary		0.008	mg	100000	806
Redistribution Layer	Other inorganic materials	0.186	mg	supplier	Alloy	Cu	7440-50-8		0.186	mg	1000000	18095
Plating Seed layer 2	Other inorganic materials	0.011	mg	supplier	Alloy	Ti	7440-32-6		0.002	mg	200963	212
				supplier	Alloy	Cu	7440-50-8		0.009	mg	799037	842
Re-passivatipon layer (HD8820)	Other organic materials	0.073	mg	supplier	Polymer	Proprietary polymer	Proprietary		0.065	mg	900000	6374
				supplier	Polymer	Additives	Proprietary		0.007	mg	100000	708
Solder ball (SAC405)	Solder	1.527	mg	supplier	Solder	Sn	7440-31-5		1.458	mg	955000	142204
				supplier	Solder	Ag	7440-22-4		0.061	mg	40000	5956
				supplier	Solder	Cu	7440-50-8		0.008	mg	5000	745
BSC (LC86R25)	Other Organic Materials	0.394	mg	supplier	polymer	Polyethylene terephthalate	25038-59-9		0.256	mg	650000	24963
				supplier	polymer	Silicon dioxide	7631-86-9		0.077	mg	195000	7489
				supplier	polymer	Plastic: EP - Epoxide, Epoxy	Proprietary		0.030	mg	75000	2880
				supplier	polymer	Proprietary Material-Other acrylic resins	Proprietary		0.030	mg	75000	2880
				supplier	polymer	Carbon black	1333-86-4		0.002	mg	5000	192